

# Chi Zhang

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/1778271/publications.pdf>

Version: 2024-02-01

10  
papers

389  
citations

1163117

8  
h-index

1474206

9  
g-index

10  
all docs

10  
docs citations

10  
times ranked

378  
citing authors

| #  | ARTICLE  | IF   | CITATIONS |
|----|--|------|-----------|
| 1  | Integrated cooling (i-Cool) textile of heat conduction and sweat transportation for personal perspiration management. <i>Nature Communications</i> , 2021, 12, 6122.   | 12.8 | 86        |
| 2  | Extreme Two-Phase Cooling from Laser-Etched Diamond and Conformal, Template-Fabricated Microporous Copper. <i>Advanced Functional Materials</i> , 2017, 27, 1703265.   | 14.9 | 83        |
| 3  | Quasi-ballistic Electronic Thermal Conduction in Metal Inverse Opals. <i>Nano Letters</i> , 2016, 16, 2754-2761.   | 9.1  | 72        |
| 4  | Approaching the limits of two-phase boiling heat transfer: High heat flux and low superheat. <i>Applied Physics Letters</i> , 2015, 107, .   | 3.3  | 53        |
| 5  | Enhanced Capillary-Driven Boiling in Copper Inverse Opals via Template Sintering. <i>Advanced Functional Materials</i> , 2018, 28, 1803689.  | 14.9 | 46        |
| 6  | Tailoring Permeability of Microporous Copper Structures through Template Sintering. <i>ACS Applied Materials &amp; Interfaces</i> , 2018, 10, 30487-30494.   | 8.0  | 18        |
| 7  | Design and optimization of well-ordered microporous copper structure for high heat flux cooling applications. <i>International Journal of Heat and Mass Transfer</i> , 2021, 173, 121241.                                  | 4.8  | 15        |
| 8  | Enhanced Heat Transfer Using Microporous Copper Inverse Opals. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2018, 140, .   | 1.8  | 11        |
| 9  | A method for quantifying in plane permeability of porous thin films. <i>Journal of Colloid and Interface Science</i> , 2018, 530, 667-674.   | 9.4  | 5         |
| 10 | Bicontinuous Mesoporous Metal Foams with Enhanced Conductivity and Tunable Pore Size and Porosity via Electrodeposition for Electrochemical and Thermal Systems. <i>ACS Applied Nano Materials</i> , 2020, 3, 12408-12415. | 5.0  | 0         |